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FDT459N

N-Channel Enhancement Mode Field Effect Transistor

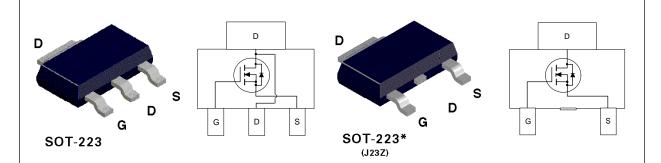
General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance, provide superior switching performance. These products are well suited to low voltage, low current applications such as notebook computer power management, battery powered circuits, and DC motor control.

Features

- 6.5 A, 30 V. $R_{DS(ON)} = 0.035\Omega$ @ $V_{GS} = 10$ V $R_{DS(ON)} = 0.055~\Omega$ @ $V_{GS} = 4.5$ V.
- High density cell design for extremely low R_{DS(ON)}.
- High power and current handling capability in a widely used surface mount package.





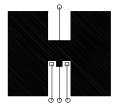
Absolute Maximum Ratings $T_A = 25^{\circ}\text{C}$ unless otherwise noted

Parameter		FDT459N	Units
Drain-Source Voltage		30	V
Gate-Source Voltage - Continuous		±20	V
Maximum Drain Current - Continuous (Note 1a)		6.5	A
- Pulsed		20	
Maximum Power Dissipation	(Note 1a)	3	W
	(Note 1b)	1.3	
	(Note 1c)	1.1	
Operating and Storage Temperature Range		-55 to 150	°C
L CHARACTERISTICS			
Thermal Resistance, Junction-to-Am	bient (Note 1a)	42	°C/W
Thermal Resistance, Junction-to-Cas	SE (Note 1)	12	°C/W
	Drain-Source Voltage Gate-Source Voltage - Continuous Maximum Drain Current - Continuou - Pulsed Maximum Power Dissipation Operating and Storage Temperature CHARACTERISTICS Thermal Resistance, Junction-to-Am	Drain-Source Voltage Gate-Source Voltage - Continuous Maximum Drain Current - Continuous - Pulsed Maximum Power Dissipation (Note 1a) (Note 1b) (Note 1c) Operating and Storage Temperature Range CHARACTERISTICS Thermal Resistance, Junction-to-Ambient (Note 1a)	Drain-Source Voltage 30 Gate-Source Voltage - Continuous ±20 Maximum Drain Current - Continuous (Note 1a) 6.5 - Pulsed 20 Maximum Power Dissipation (Note 1a) (Note 1b) (Note 1b) 1.3 (Note 1c) (Note 1c) 1.1 Operating and Storage Temperature Range -55 to 150 L CHARACTERISTICS Thermal Resistance, Junction-to-Ambient (Note 1a) 42

^{*} Order option J23Z for cropped center drain lead.

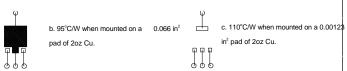
Symbol	Parameter	Conditions		Min	Тур	Max	Units
OFF CHAR	ACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		30			V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient	$I_D = 250 \mu\text{A}$, Referenced to	I _D = 250 μA, Referenced to 25 °C		33		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V				1	μA
			T _J =55°C			10	μA
GSSF	Gate - Body Leakage, Forward	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$				100	nA
GSSR	Gate - Body Leakage, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
ON CHARA	CTERISTICS (Note 2)	·					
/ _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		1	1.6	2	V
$\Delta V_{GS(th)}/\Delta T_{J}$	Gate Threshold Voltage Temp.Coefficient	I _D = 250 μA, Referenced to	25 °C		-4.2		mV/°C
	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 6.5 \text{ A}$			0.031	0.035	Ω
			T _J =125°C		0.044	0.06	
		$V_{GS} = 4.5 \text{ V}, I_{D} = 5.5 \text{ A}$			0.046	0.055	
D(ON)	On-State Drain Current	$V_{GS} = 10 \text{ V}, V_{DS} = 5 \text{ V}$		20			Α
Fs	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 6.5 \text{ A}$			16		S
OYNAMIC C	CHARACTERISTICS						
iss	Input Capacitance	$V_{DS} = 15 \text{ V}, \ V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz}$			365		pF
oss	Output Capacitance				210		pF
rss	Reverse Transfer Capacitance				70		pF
WITCHING	G CHARACTERISTICS (Note 2)						
O(on)	Turn - On Delay Time	$V_{DD} = 15 \text{ V}, I_{D} = 1 \text{ A},$			5.2	11	ns
	Turn - On Rise Time	$V_{GS} = 10 \text{ V}, \ R_{GEN} = 6 \Omega$			8.2	16	ns
D(off)	Turn - Off Delay Time				6	12	ns
1	Turn - Off Fall Time				16	26	ns
Q_g	Total Gate Charge	$V_{DS} = 10 \text{ V}, I_D = 6.5 \text{ A},$ $V_{GS} = 10 \text{ V}$			12	17	nC
Q_{gs}	Gate-Source Charge				2.2		nC
Q_{gd}	Gate-Drain Charge				3		nC
RAIN-SOU	IRCE DIODE CHARACTERISTICS AND MA	XIMUM RATINGS			ı	ı	
3	Maximum Continuous Drain-Source Diode Forward Current				2.5	Α	
/ _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2.5 \text{ A} \text{ (Note 2)}$			0.8	1.2	V

Typical $R_{_{\theta^{J\!A}}}$ using the board layouts shown below on $\,$ FR-4 PCB in a still air environment:



a. 42°C/W when mounted on a 1 in² pad of 2oz Cu.





Scale 1: 1 on letter size paper 2. Pulse Test: Pulse Width $\leq 300 \mu s$, Duty Cycle $\leq 2.0\%$

^{1.} $R_{g,u}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{g,c}$ is guaranteed by design while $\boldsymbol{R}_{\text{\tiny BCA}}$ is determined by the user's board design.

Typical Electrical Characteristics

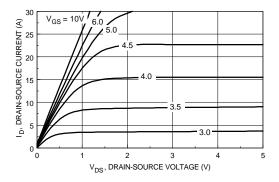


Figure 1. On-Region Characteristics.

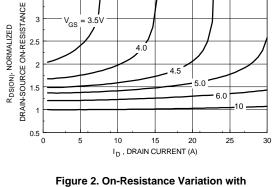


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

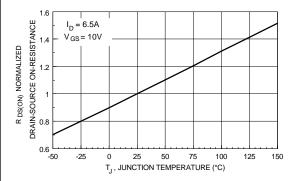


Figure 3. On-Resistance Variation with Temperature.

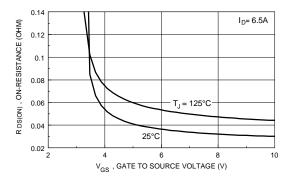


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

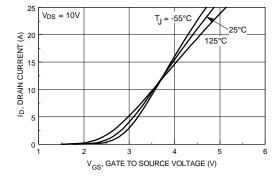


Figure 5. Transfer Characteristics.

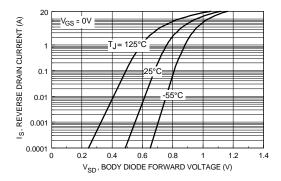


Figure 6. Body Diode Forward Voltage
Variation with Source Current
and Temperature.

Typical Electrical Characteristics

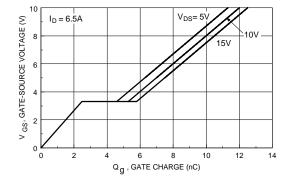


Figure 7. Gate Charge Characteristics.

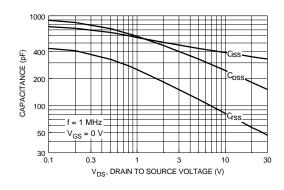


Figure 8. Capacitance Characteristics.

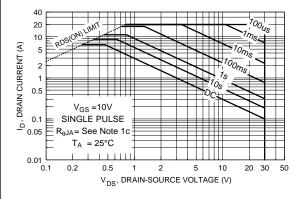


Figure 9. Maximum Safe Operating Area.

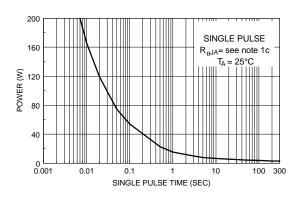


Figure 10. Single Pulse Maximum Power Dissipation.

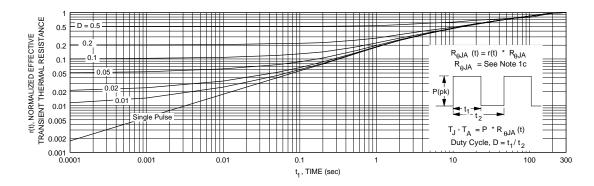


Figure 11. Transient Thermal Response Curve.

Note: Thermal characterization performed using the conditions described in note 1c. Transient thermal response will change depending on the circuit board design.

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